

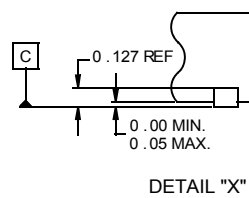
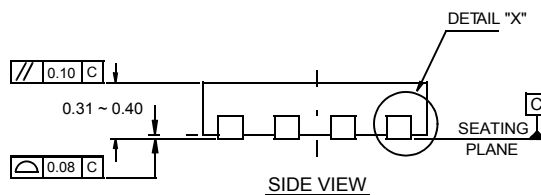
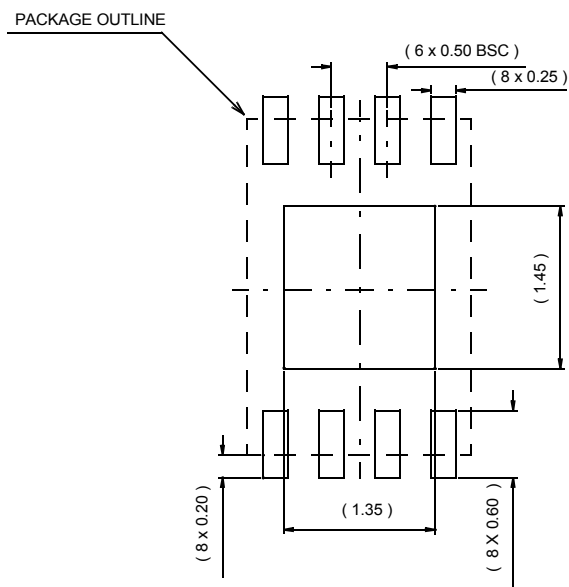
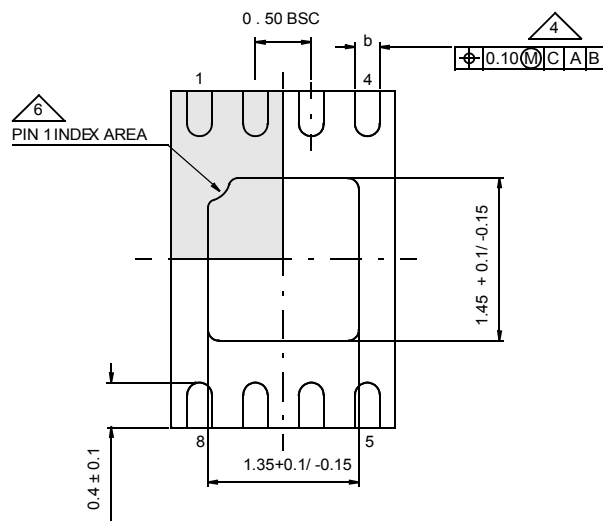
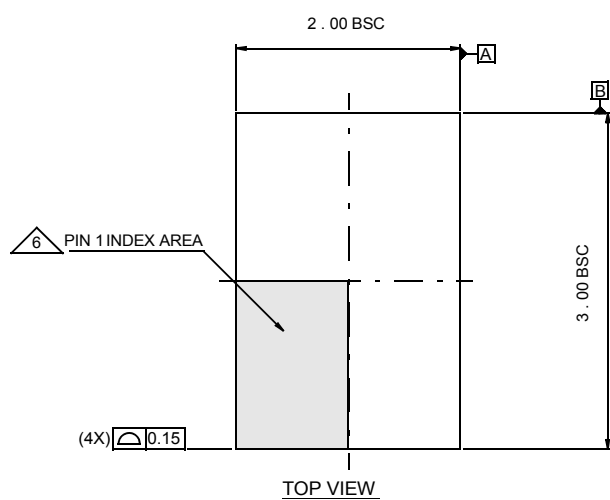
# Plastic Packages for Integrated Circuits

## Package Outline Drawing

### L8.2x3B

#### 8 LEAD EXTREME THIN DUAL FLAT NO-LEAD PLASTIC PACKAGE (XDFN)

Rev 2, 05/15



#### NOTES:

- Dimensions are in millimeters.  
Dimensions in ( ) for Reference Only.
- Dimensioning and tolerancing conform to ASME Y14.5m-1994.
- Unless otherwise specified, tolerance : Decimal  $\pm 0.05$
- Dimension b applies to the metallized terminal and is measured between 0.18mm and 0.30mm from the terminal tip.
- Tiebar shown (if present) is a non-functional feature and may be located on any of the 4 sides (or ends).
- The configuration of the pin #1 identifier is optional, but must be located within the zone indicated. The pin #1 identifier may be either a mold or mark feature.
- Package thickness does not include any sawing burr as part of thickness measurement.